

# **STY60NM60**

# N-CHANNEL 600V - 0.050Ω - 60A Max247 Zener-Protected MDmesh<sup>™</sup>Power MOSFET

TARGET DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STY60NM60	600V	< 0.06Ω	60 A

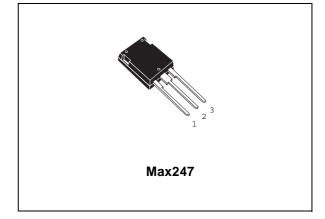
- TYPICAL  $R_{DS}(on) = 0.050\Omega$
- HIGH dv/dt AND AVALANCHE CAPABILITIES
- 100% AVALANCHE TESTED
- LOW INPUT CAPACITANCE AND GATE CHARGE
- LOW GATE INPUT RESISTANCE
- TIGHT PROCESS CONTROL
- INDUSTRY'S LOWEST ON-RESISTANCE

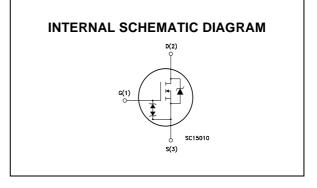
# DESCRIPTION

The MDmesh<sup>™</sup> is a new revolutionary MOSFET technology that associates the Multiple Drain process with the Company's PowerMESH™ horizontal layout. The resulting product has an outstanding low on-resistance, impressively high dv/dt and excellent avalanche characteristics. The adoption of the Company's proprietary strip technique yields overall dynamic performance that is significantly better than that of similar competition's products.

### **APPLICATIONS**

The MDmesh<sup>™</sup> family is very suitable for increasing power density of high voltage converters allowing system miniaturization and higher efficiencies.





Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>DGR</sub>	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	600	V
V <sub>GS</sub>	Gate- source Voltage	±30	V
ID	Drain Current (continuos) at T <sub>C</sub> = 25°C	60	А
ID	Drain Current (continuos) at T <sub>C</sub> = 100°C	37.8	А
I <sub>DM</sub> (•)	Drain Current (pulsed)	240	А
P <sub>TOT</sub>	Total Dissipation at $T_C = 25^{\circ}C$	450	W
V <sub>ESD(G-S)</sub>	Gate source ESD(HBM-C=100pF, R=15KΩ)	4	KV
	Derating Factor	3.6	W/°C
dv/dt	Peak Diode Recovery voltage slope	6	V/ns
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Ti	Max. Operating Junction Temperature	150	°C

### **ABSOLUTE MAXIMUM RATINGS**

# STY60NM60

# THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	0.277	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	30	°C/W
ΤI	Maximum Lead Temperature For Soldering Purpose	300	°C

# **AVALANCHE CHARACTERISTICS**

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max)	30	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting $T_j = 25 \text{ °C}$ , $I_D = I_{AR}$ , $V_{DD} = 35 \text{ V}$ )	1350	mJ

# **ELECTRICAL CHARACTERISTICS** (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	600			V
I <sub>DSS</sub>	Zero Gate Voltage	V <sub>DS</sub> = Max Rating			10	μA
	Drain Current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max Rating, $T_{C}$ = 125 °C			100	μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	$V_{GS} = \pm 30V$			±100	nA

# ON (1)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3	4	5	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A		0.050	0.06	Ω

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	$V_{DS} = I_{D(on)} \times R_{DS(on)max,}$ $I_{D} = 30A$		20		S
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25V, f = 1 \text{ MHz}, V_{GS} = 0$		4430		pF
Coss	Output Capacitance			733		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			54		pF
R <sub>G</sub>	Gate Input Resistance	f=1 MHz Gate DC Bias = 0 Test Signal Level = 20mV Open Drain		1.5		Ω

Note: 1. Pulsed: Pulse duration =  $300 \ \mu$ s, duty cycle 1.5 %.



# ELECTRICAL CHARACTERISTICS (CONTINUED) SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on Delay Time	$V_{DD} = 250V, I_D = 30A$		TBD		ns
t <sub>r</sub>	Rise Time	$R_G = 4.7\Omega V_{GS} = 10V$ (see test circuit, Figure 3)		TBD		ns
Qg	Total Gate Charge	$V_{DD} = 400V, I_D = 60A,$		104	145	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10V		TBD		nC
Q <sub>gd</sub>	Gate-Drain Charge			TBD		nC

### SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>r(Voff)</sub>	Off-voltage Rise Time	$V_{DD} = 400V, I_D = 60A,$		TBD		ns
t <sub>f</sub>	Fall Time	$R_G = 4.7\Omega$ , $V_{GS} = 10V$ (see test circuit, Figure 5)		TBD		ns
t <sub>c</sub>	Cross-over Time			TBD		ns

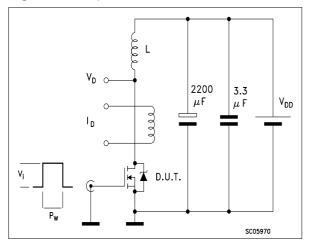
# SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain Current				60	А
I <sub>SDM</sub> (2)	Source-drain Current (pulsed)				240	А
V <sub>SD</sub> (1)	Forward On Voltage	$I_{SD} = 60A, V_{GS} = 0$			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 60A, di/dt = 100A/µs,		TBD		ns
Qrr	Reverse Recovery Charge	V <sub>DD</sub> = 60V, T <sub>j</sub> = 150°C (see test circuit, Figure 5)		TBD		μC
I <sub>RRM</sub>	Reverse Recovery Current			TBD		А

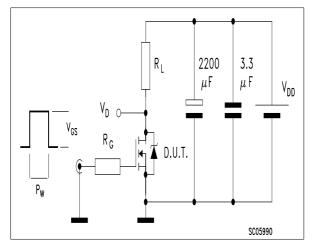
Note: 1. Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.
2. Pulse width limited by safe operating area.

# STY60NM60

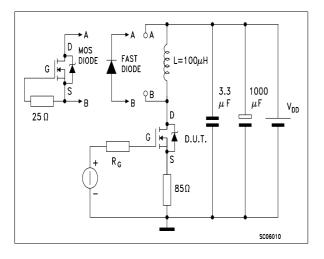
Fig. 1: Unclamped Inductive Load Test Circuit



**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



# Fig. 2: Unclamped Inductive Waveform

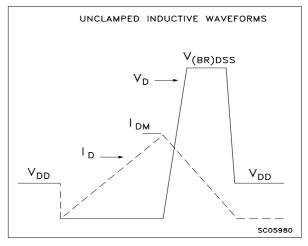
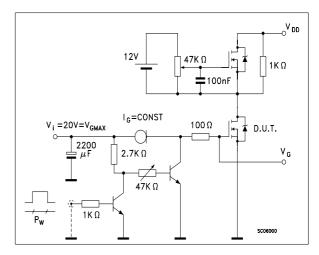


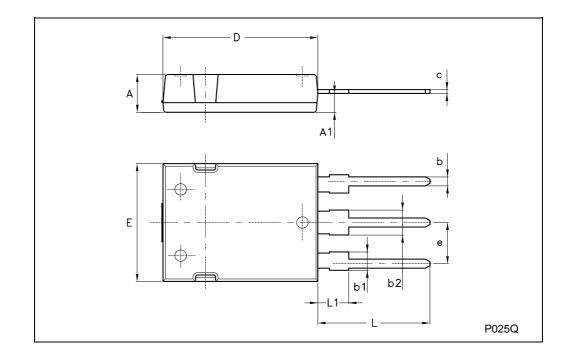
Fig. 4: Gate Charge test Circuit



57.

DIM.		mm		inch			
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	4.70		5.30				
A1	2.20		2.60				
b	1.00		1.40				
b1	2.00		2.40				
b2	3.00		3.40				
с	0.40		0.80				
D	19.70		20.30				
е	5.35		5.55				
Е	15.30		15.90				
L	14.20		15.20				
L1	3.70		4.30				

## Max247 MECHANICAL DATA



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